

REMARKS

Claims 1-21 are pending in this application. By this Amendment, Applicants amend claims 1, 9, 13 and 14.

The drawings were objected to because the recess provided on the first and second case disclosed in Claims 11 and 12 was not shown. Applicants have amended Fig. 2 in the attached Request for Approval of Proposed Drawing Corrections to correct this informality. Accordingly, Applicants respectfully request reconsideration and withdrawal of the objections to the drawings.

Claims 1-21 were rejected under 35 USC Section 112, second paragraph, for being indefinite. Claims 1, 9, 13 and 14 have been amended to correct most of the informalities noted by the Examiner. However, with respect to the Examiner's question concerning the external electrodes extending over the lower surface and on the side of the body, Applicants respectfully submit that the claims clearly recite this feature which is shown in the drawing figures and described in the specification. The Examiner questioned which body the external electrodes extend over the lower surface and side of the body and indicated that it seemed from Figure 7 that the electrode 19 is extending on the side surface but not the bottom surface, but then the Examiner stated that "the other bottom surface electrodes are 18 and 19." The Examiner also questioned whether the same electrode was extending from the side surface to the lower surface. As is clearly shown in the drawings and clearly explained in the specification and clearly recited in the claims, each one of the electrodes 18, 19, 20 extend across the top surface of the body of the chip electronic component (uppermost surface of the chip electronic component body shown in Fig. 7) across the side edge surfaces (longitudinal side edges surfaces in Fig. 7) and across the bottom surface of the chip electronic component body (surface shown in projection in lower portion of Fig. 7, e.g. the surface shown in Fig. 7 that includes the narrow portions 18a, 19a, 20a and the wide portions 18b, 19b and 20b). Thus, it is absolutely clear that the external electrodes in Fig. 7 and other embodiments shown in the drawings and described in the specification extend over at least the lower surface and at least one of the side surfaces of said body of the

Serial No. 09/656,106
August 16, 2002
Page 5

chip electronic component. Accordingly, the claims are absolutely clear and definite. Accordingly, Applicants respectfully request reconsideration and withdrawal of the rejection of Claims 1-21 under 35 USC Section 112, second paragraph.

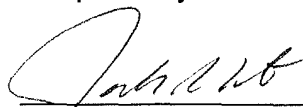
Claims 1, 2, 6-12, 14-18, 20 and 21 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Gamo (U.S. Patent No. 6,011,451) in view of Kuroda et al. (U.S. Patent No. 6,215,229). Claims 3-5 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Gamo and Kuroda further in view of Danov (U.S. 6,188,163). Claims 13 and 19 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Gamo and Kuroda and further in view of Okeshi (U.S. 6,192,562). These rejections are respectfully traversed.

Applicant submits herewith a Declaration under 37 C.F.R. § 1.130 which indicates that the present invention and the inventions described in Gamo (U.S. Patent No. 6,011,451), Kuroda et al. (U.S. Patent No. 6,215,229) and Okeshi (U.S. 6,192,562) were at the time the inventions were made, commonly owned by the same company. Accordingly, Applicant respectfully submits that Gamo, Kuroda et al. and Okeshi cannot be applied in an obviousness rejection under 35 U.S.C. § 103(a) in the present application.

In view of the foregoing, Applicants respectfully submit that claims 1-21 are allowable and that this application is in condition for allowance. Favorable consideration and prompt allowance are respectfully solicited.

Respectfully submitted,

Date: August 16, 2002



Attorneys for Applicant

Joseph R. Keating
Registration No. 37,368

KEATING & BENNETT LLP
10400 Eaton Place, Suite 312
Fairfax, VA 22030
Telephone: (703) 385-5200

VERSION WITH MARKINGS SHOWING CHANGES MADE

1. A chip electronic component comprising:
 - a body of the chip electronic component having outer peripheral surfaces including an upper surface, a lower surface and a pair of side surfaces;
 - an electronic component element having electrodes and [being included in] defining part of said body of the chip electronic component; and
 - a plurality of external electrodes arranged to extend over at least the lower surface and at least one of the side surfaces of said body of the chip electronic component and electrically connected to the electrodes of the electronic component element; wherein
 - each portion of said external electrodes provided on the lower surface of said body of the chip electronic component is provided with a narrow portion and a wide portion.
9. The chip electronic component according to claim 8, further comprising a [the] second case substrate [laminated] disposed on the upper surface of said piezoelectric resonant element so as not to hinder the vibration of the piezoelectric resonant element.
13. A mounting structure of a chip electronic component according to claim 1, wherein a bonding portion defined by a conductive bond [is located inside of] does not extend outside of an outer periphery of the chip electronic component as seen from the top of the chip electronic component.
14. A chip electronic component comprising:
 - a body of the chip electronic component having outer peripheral surfaces including an upper surface, a lower surface and a pair of side surfaces;
 - an electronic component element having electrodes and [being included in] defining part of said body of the chip electronic component; and

a plurality of external electrodes arranged so as to extend over at least the lower surface and at least one of the side surfaces of said body of the chip electronic component and electrically connected to the electrodes of the electronic component element;

wherein each portion of said external electrodes provided on the lower surface of said body of the chip electronic component is arranged to have an almost uniform width from one longitudinal end to the other, and satisfy the relation $L_1 < L_3$, where L_3 is the width of each portion of the external electrodes provided on the lower surface of said body of the chip electronic component, and L_1 is the width of each portion of the external electrodes provided on the at least one side surface of said body of the chip electronic component.